



## Dissemination Factsheets

### SEMI Europe 3D and Systems Summit 2022

#### About the 3D and Systems Summit 2022

Leading experts in 3D integration and systems for semiconductor manufacturing applications have gathered at the annual SEMI 3D & Systems Summit, 14-15 June, 2022, in Dresden for insights into the latest heterogeneous integration innovations for semiconductor applications enabling the future of intelligent systems. Focused on innovation for smart manufacturers, the Summit highlighted premier technologies and processes enabling greater productivity solutions for Europe's key industries.

Among numerous industry players, the 3D & Systems Summit presenters included experts from across the global innovation and technology landscape such as AT&S, Atotech, Besi, CEA-Leti, DeepXscan, ETH Zurich, EV Group (EVG), Evatec AG, Fraunhofer IZM, GlobalFoundries, imec, Intel Deutschland GmbH, KLA, Merck Group, NanoWired GmbH, Siemens EDA, SENTECH, Sipearl, SPTS Technologies, SÜSS MicroTec, TechSearch, and Yole Développement. Exhibition and Networking

The most prominent names in 3D integration microelectronics manufacturing had the opportunity to showcase their latest products and technologies at the exhibition area, including: adeia, AEMtec, BESI, Canon Anelva Corporation, Confovis, Evatec, EV Group, FormFactor FRT Metrology, Fraunhofer IZM-ASSID, HEIDENHAIN, Integrated Dynamics Engineering, Koh Young Europe GmbH, LPKF Laser & Electronics AG, OPTIM Wafer Services, Polyteknik AS, RENA, SENTECH and several EU-funded projects.

As premier event, the summit also featured business-to-business matchmaking and networking for participants to explore new partnerships, ventures and other business opportunities.



Figure 1: 3D and Systems Summit Opening Session



Figure 2: 3D and Systems Summit Networking and Partnership Lounge

## MADEIN4 Dissemination and Exploitation at 3D and Systems Summit 2022

As key European innovation project, the MADEIN4 consortium was a welcomed addition to the 3D and Systems Summit 2022 to share its achievements and views on the future of Industry 4.0 manufacturing. The dissemination of the project was conducted among highly influential audiences from every segment of the global microelectronics industry, including C-level executives, leading manufacturers, key technology stakeholders and purchasers. By focusing on the core objective of engaging businesses and professional as potential future beneficiaries of MADEIN4 delivered innovation, the possibility to engage the consortium representatives and project in a direct way proved to be an excellent way to connect with potential stakeholders and collect insight on potential applications of MADEIN4 achievements across industries.

To disseminate and exploit knowledge and project achievements efficiently throughout the entire duration of the 3D and Systems Summit 2022 event, the MADEIN4 project was featured as premier collaborative initiative in the 3D and Systems Summit Engagement Lounge (Figure 1 and 2), centered around innovation delivered by EU-funded collaborations. Focused on dissemination of critical innovation objectives and achievements, the promotion of MADEIN4 key technologies and project partners was linked through a networking area with visual presentation of the project. The dissemination within the 3D and Systems Summit Engagement Lounge served as ground for showcasing the innovation potential and opportunities of EU funded projects, their impact on the growth of European economy, employment and leadership in key industrial sectors of the future.



Figure 3: MADEin4 Banner at 3D and Systems Summit 2022

Figure 5: 3D and Systems Summit Engagement Lounge: MADEin4 Dissemination Material

